

SOT2044-1

HUBGA182, thermal enhanced ultra thin ball grid array package, 182 terminals, 0.4 mm pitch, 6.1 mm x 6.5 mm x 0.56 mm body

10 October 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	HUBGA182
Package style descriptive code	HBGA (thermal enhanced ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	05-09-2019
Manufacturer package code	98ASA01500D

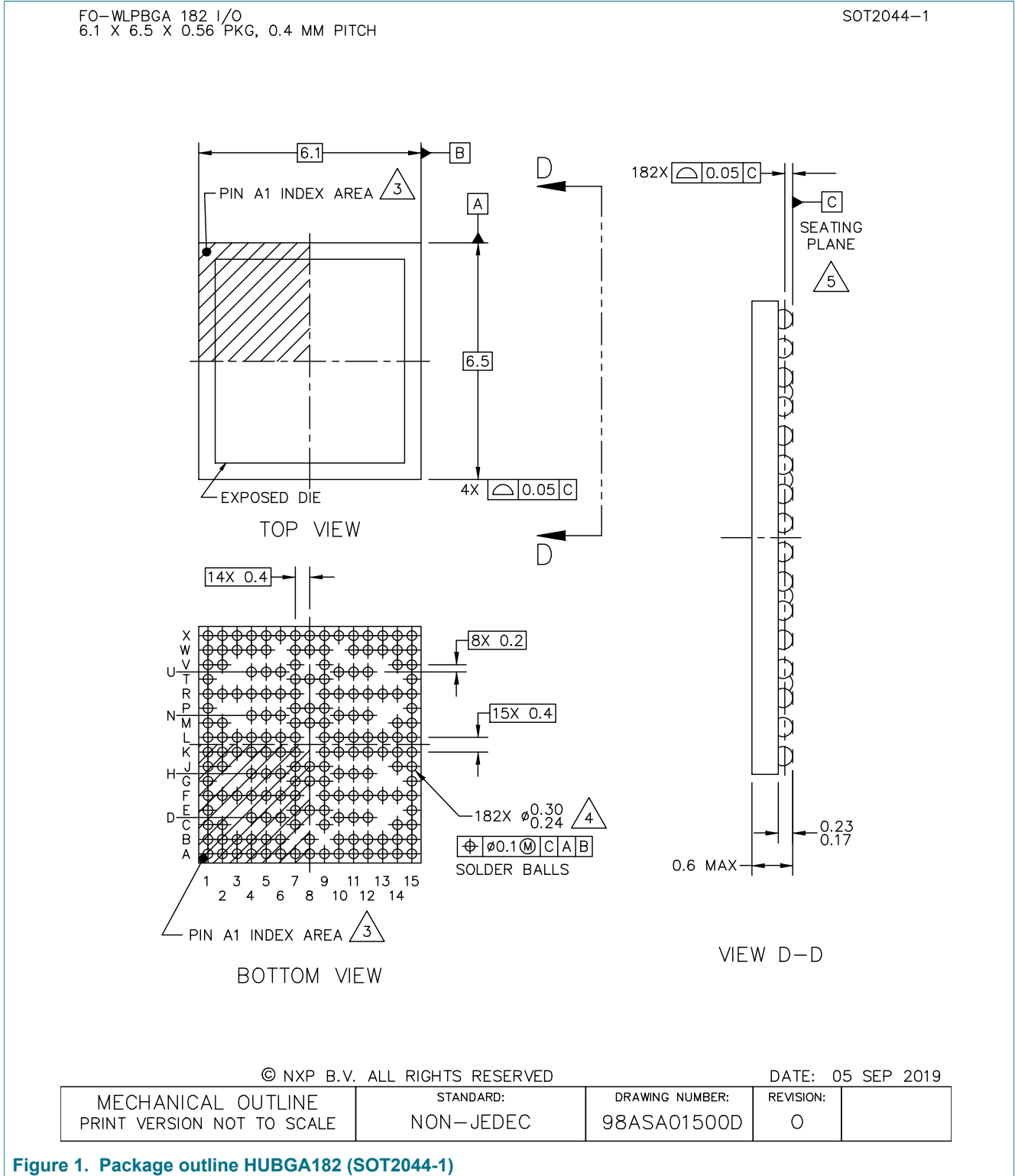
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	6.05	6.1	6.15	mm
package width	6.45	6.5	6.55	mm
seated height	-	0.56	0.6	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	182	-	



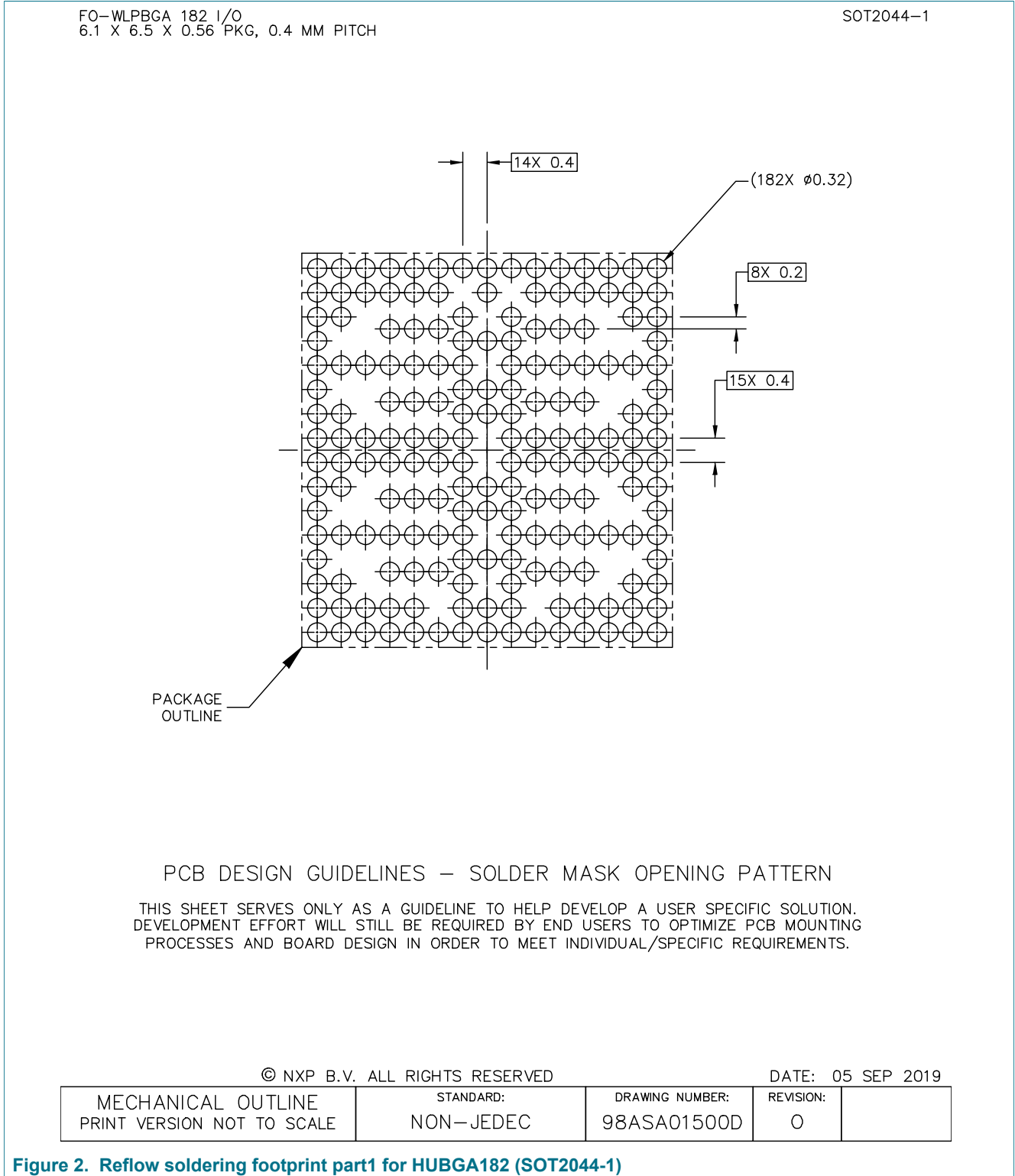
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2 Package outline



HUBGA182, thermal enhanced ultra thin ball grid array package, 182 terminals, 0.4 mm pitch, 6.1 mm x 6.5 mm x 0.56 mm body

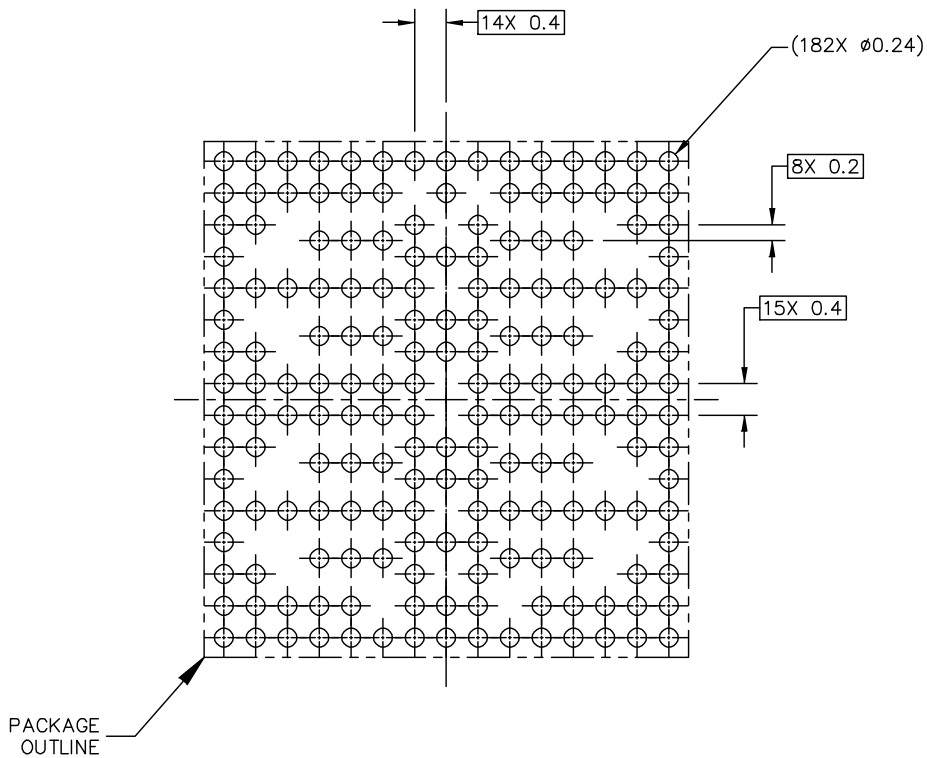
3 Soldering



HUBGA182, thermal enhanced ultra thin ball grid array package, 182 terminals, 0.4 mm pitch, 6.1 mm x 6.5 mm body

FO-WLPBGA 182 I/O
6.1 X 6.5 X 0.56 PKG, 0.4 MM PITCH

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PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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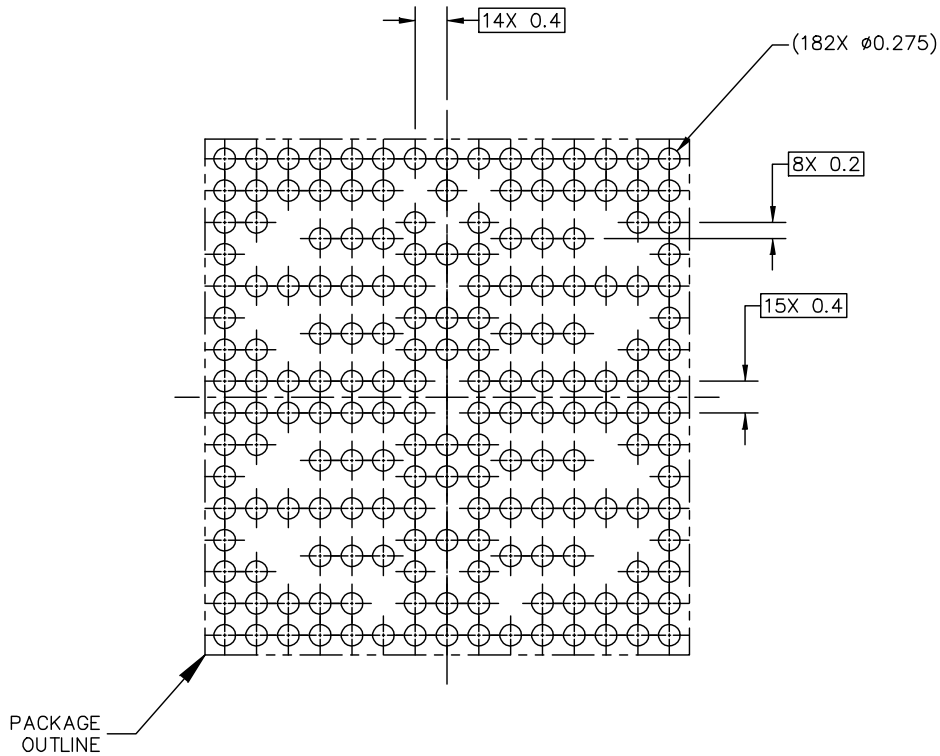
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01500D	REVISION: 0	
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Figure 3. Reflow soldering footprint part2 for HUBGA182 (SOT2044-1)

HUBGA182, thermal enhanced ultra thin ball grid array package, 182 terminals, 0.4 mm pitch, 6.1 mm x 6.5 mm body

FO-WLPBGA 182 I/O
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RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 4. Reflow soldering footprint part3 for HUBGA182 (SOT2044-1)

HUBGA182, thermal enhanced ultra thin ball grid array package, 182 terminals, 0.4 mm pitch, 6.1 mm x 6.5 mm x 0.56 mm body

FO-WLPBGA 182 I/O
6.1 X 6.5 X 0.56 PKG, 0.4 MM PITCH

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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Figure 5. Package outline note HUBGA182 (SOT2044-1)

4 Legal information

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